

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 08111426
PUBLICATION DATE : 30-04-96

APPLICATION DATE : 06-10-94
APPLICATION NUMBER : 06268249

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INT.CL. : H01L 21/52

TITLE : SEMICONDUCTOR DEVICE

ABSTRACT : PURPOSE: To obtain a semiconductor device excellent in bonding strength in which a semiconductor chip is restrained from warping while suppressing generation of void or chip crack by bonding the semiconductor chip and a lead frame through an epoxy based conductive adhesive sheet fixed separably onto a supporting film.

CONSTITUTION: Conductive adhesive in a conductive adhesive sheet contains an epoxy resin, a hardener, a thermoplastic resin having high compatibility with the epoxy resin, and a conductive powder as essential components. The epoxy resin includes bisphenol type, phenol novolak type, glycidylether type; etc. The hardener includes an amine based hardener and the thermoplastic resin having high compatibility with epoxy resin includes polyester resin. The conductive powder includes silver powder, copper powder, etc., which is admixed by 70-90% with a binder resin. An adhesive thus obtained is applied to a supporting film and dried to produce an adhesive sheet which is then heated to enhance the separation characteristics between the supporting film and the conductive adhesive.

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